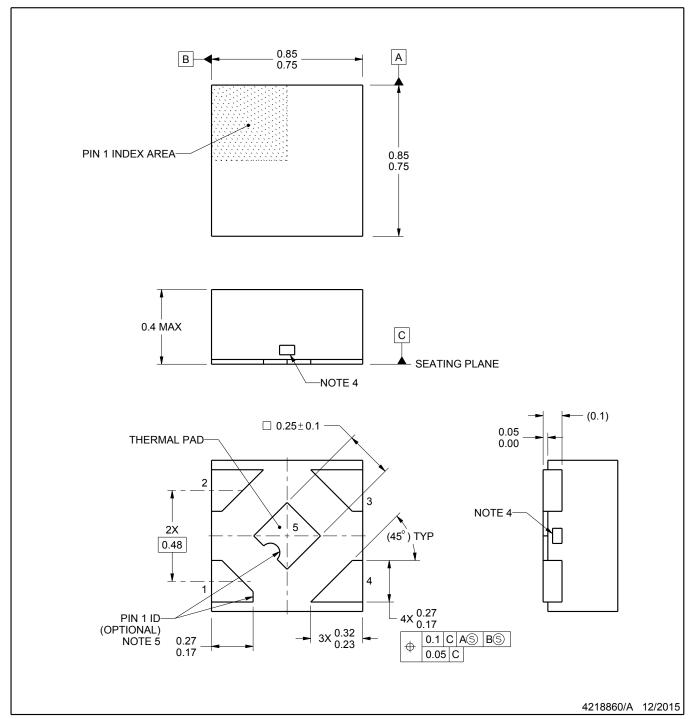


PLASTIC SMALL OUTLINE - NO LEAD



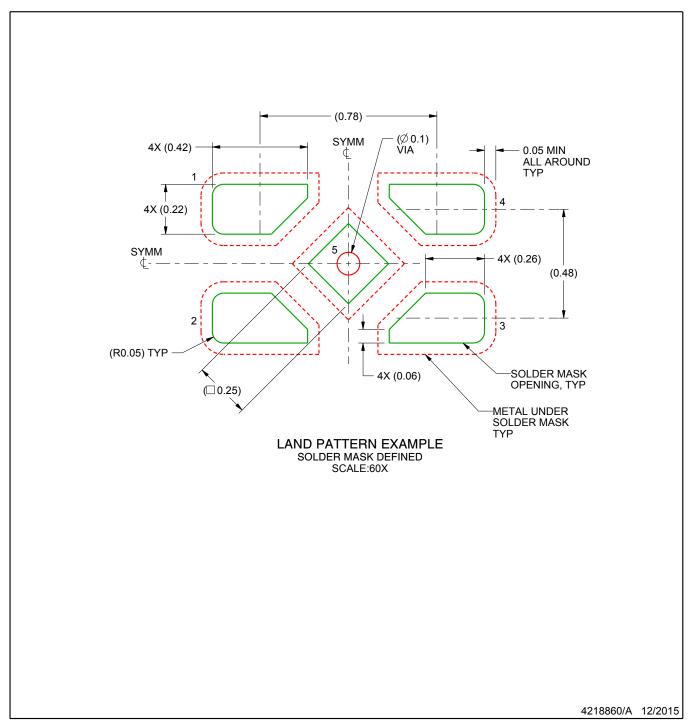
## NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.
- 3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.4. The size and shape of this feature may vary.
- 5. Features may not exist. Recommend use of pin 1 marking on top of package for orientation purposes.



PLASTIC SMALL OUTLINE - NO LEAD



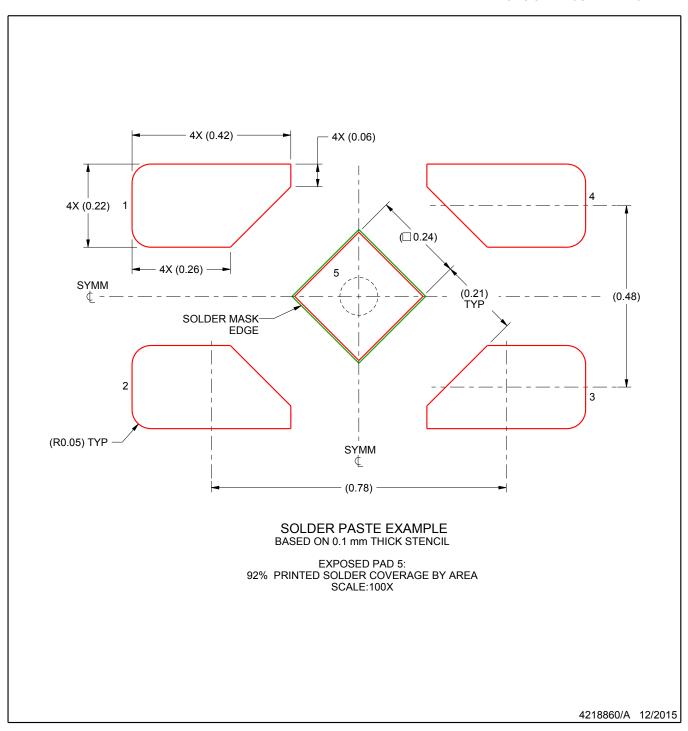
NOTES: (continued)



<sup>6.</sup> This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

<sup>7.</sup> Vias are optional depending on application, refer to device data sheet. If some or all are implemented, recommended via locations are shown.

PLASTIC SMALL OUTLINE - NO LEAD



NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



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